

MSKSEMI 美森科

SEMICONDUCTOR



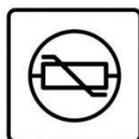
ESD



TVS



TSS



MOV



GDT



PLED

P0080TA-MS

Product specification

FEATURES

- Excellent capability of absorbing transient surge
- Quick response to surge voltage
- Eliminates over voltage caused by fast rising transients
- Solid-state silicon technology, non degenerate
- IEC61000-4-2(ESD) ±30KV(air)±30KV(contact)
- Moisture sensitivity level: Level 1

APPLICATIONS

- Audio/Video line
- Network and telecom
- Data lines and security systems
- Serial ports

APPROVALS

- **RoHS:** Compliance with 2011/65/EU
- **HF:** Compliance with IEC61249-2-21:2003

Reference News

SMA(DO-214AC)	Schematic Symbol	MARKING
		

ELECTRICAL CHARACTERISTICS

Part Number	V _{DRM}	V _S	V _T	I _{DRM}	I _S	I _T	I _H	C _o
	Min. (V)	Max. (V)	Max. (V)	Max.(μA)	mA	Max. (A)	Min.(mA)	Typ.(pF)
P0080TA-MS	6.0	25.0	4.0	5.0	800.0	2.2	20.0	25.0

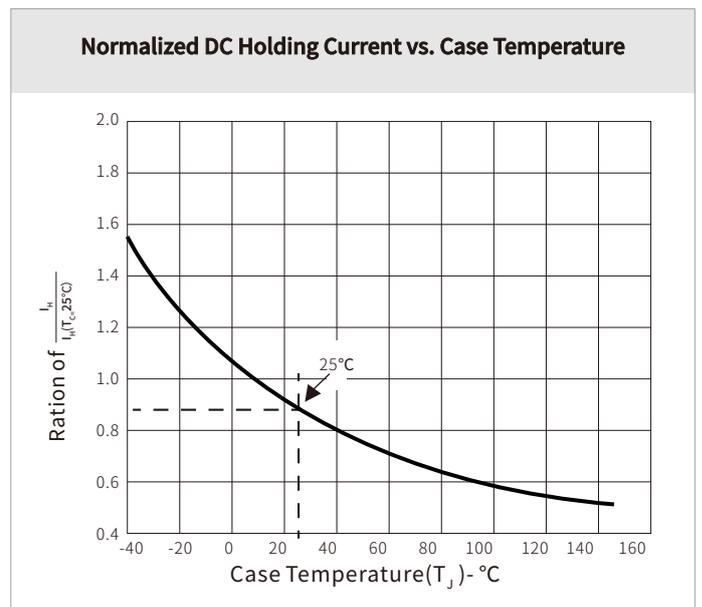
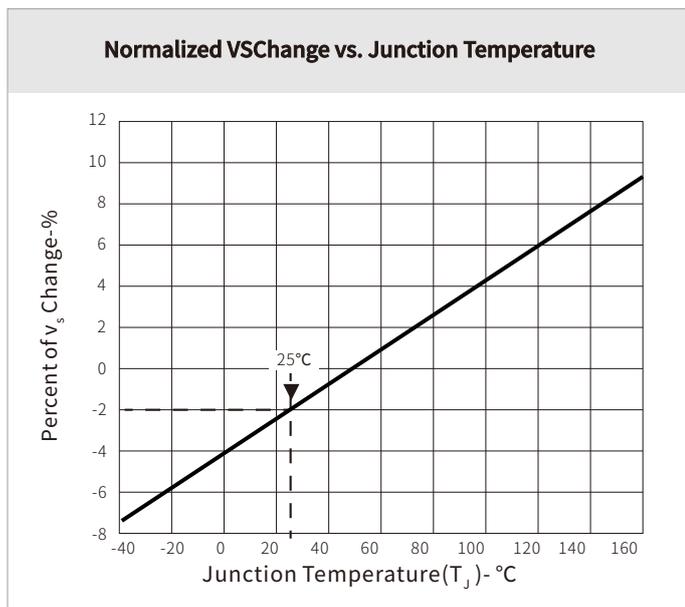
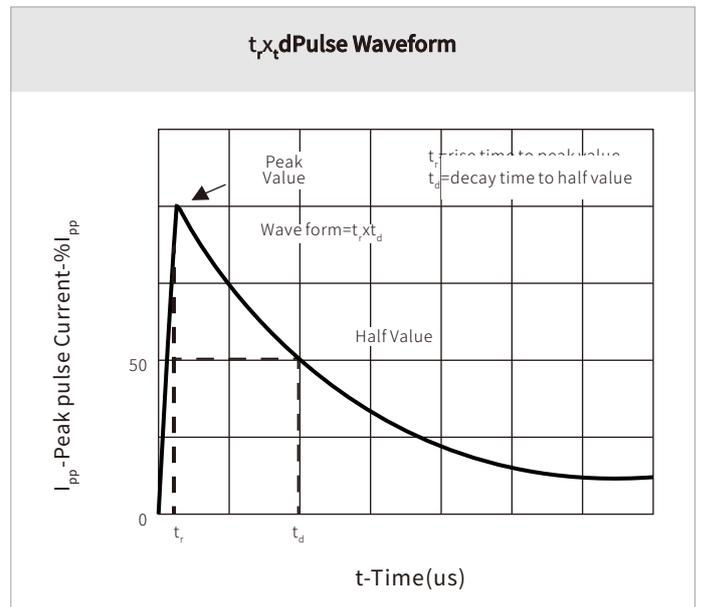
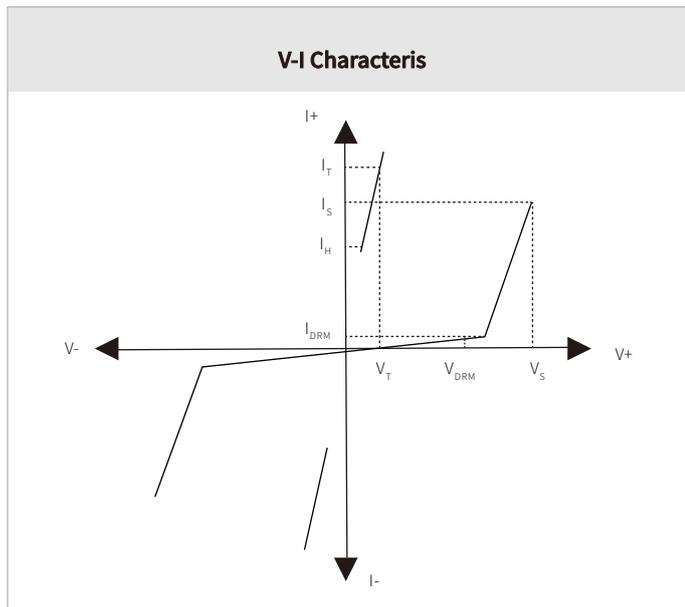
SURGE RATINGS

Part Number	V _{PP} 10x700us	I _{PP} 5x310us
	(V)	(A)
P0080TA-MS	2000	50

THERMAL CONSIDERATIONS

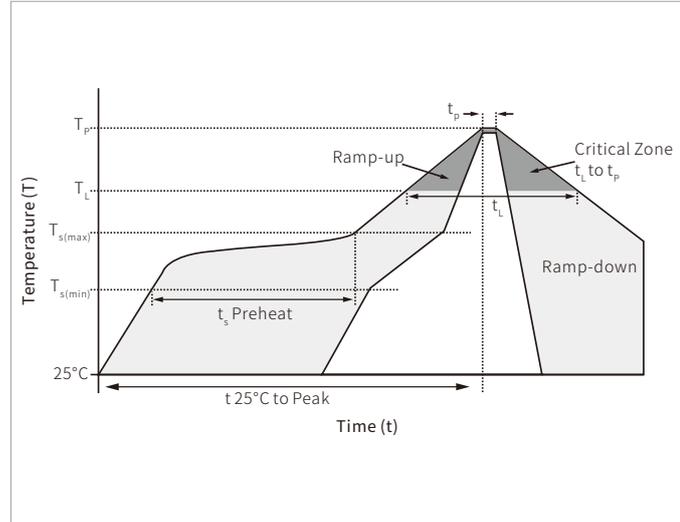
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Junction to Ambient on printed circuit	120	$^{\circ}\text{C}/\text{W}$
T_J	Operating Junction Temperature	-55 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$

RATINGS AND CHARACTERISTIC CURVES ($T_A=25^{\circ}\text{C}$)

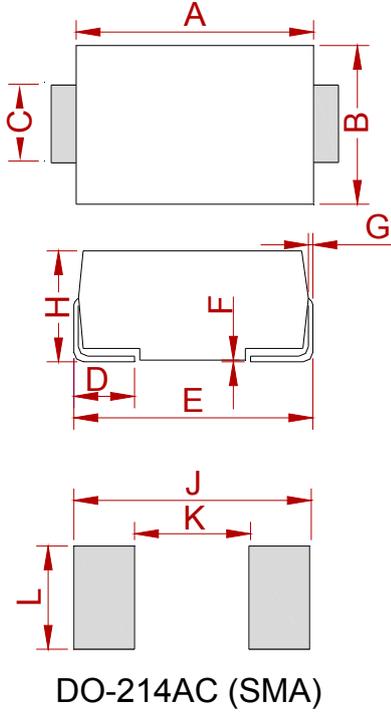


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
P0080TA-MS	DO-214AC (SMA)	7500PCS

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